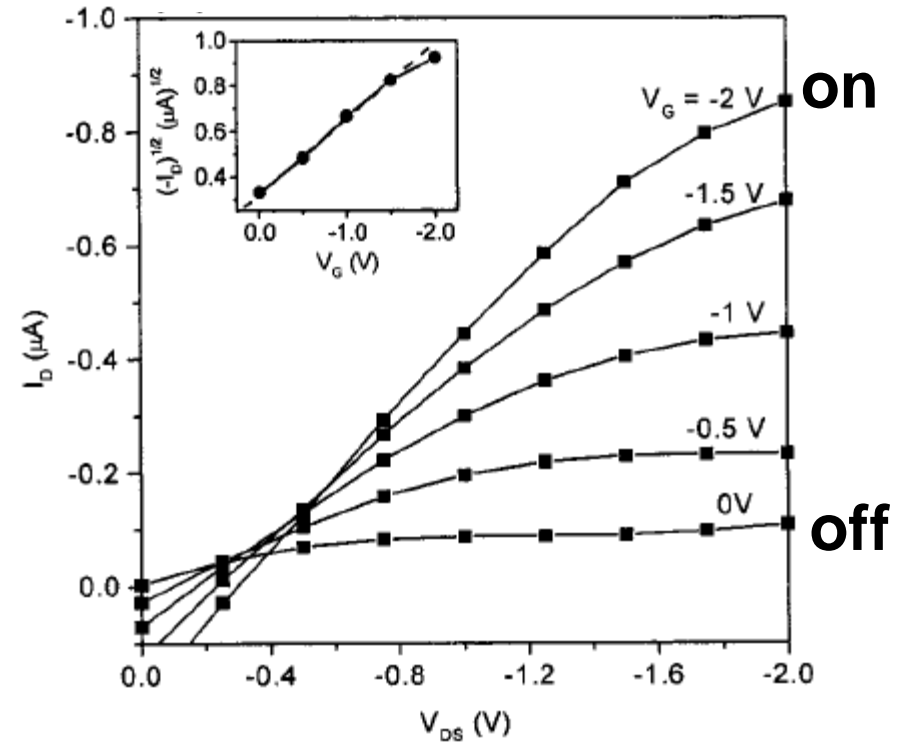
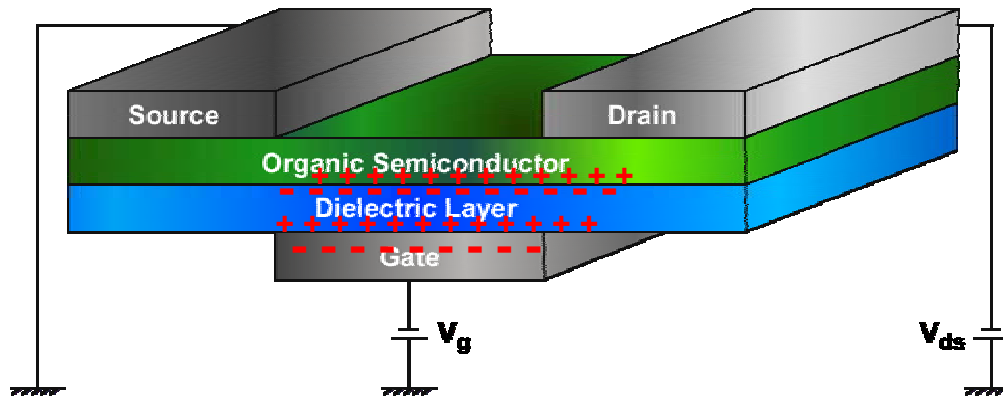


Organic Materials for Flexible Electronics

Zhenan Bao
Department of Chemical Engineering
Stanford University



Field-effect transistor (FET)



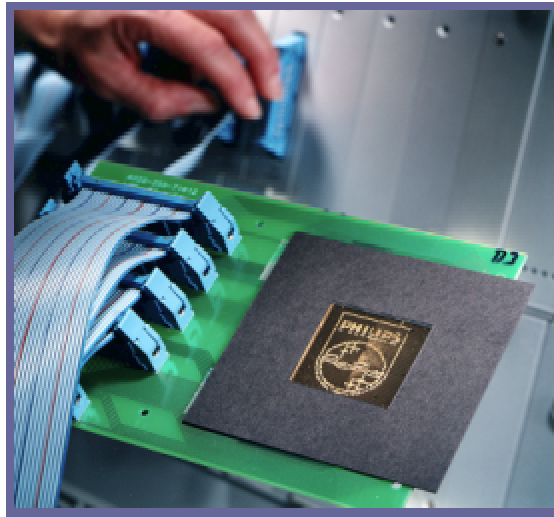
Parameters:
on/off ratio
field effect mobility

Colin C. Reese; Mark Roberts, Mang-mang Ling, Zhenan Bao; *Materials Today*, 2004, 7(9), 22.



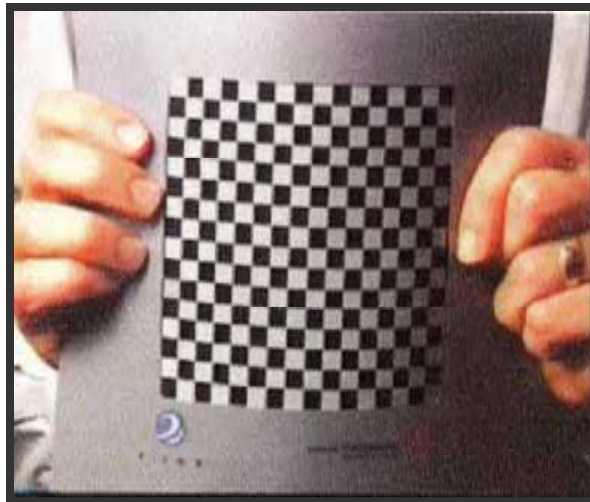
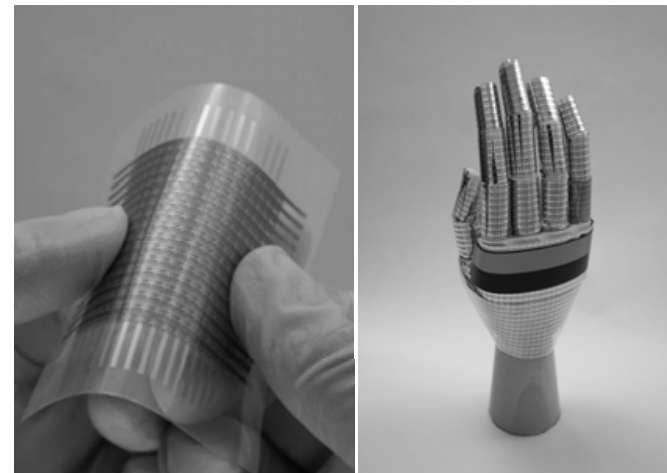
Organic Electronic Devices: Displays, Memory Cards, Sensors

-----Electronics Everywhere



Philips

Sensors

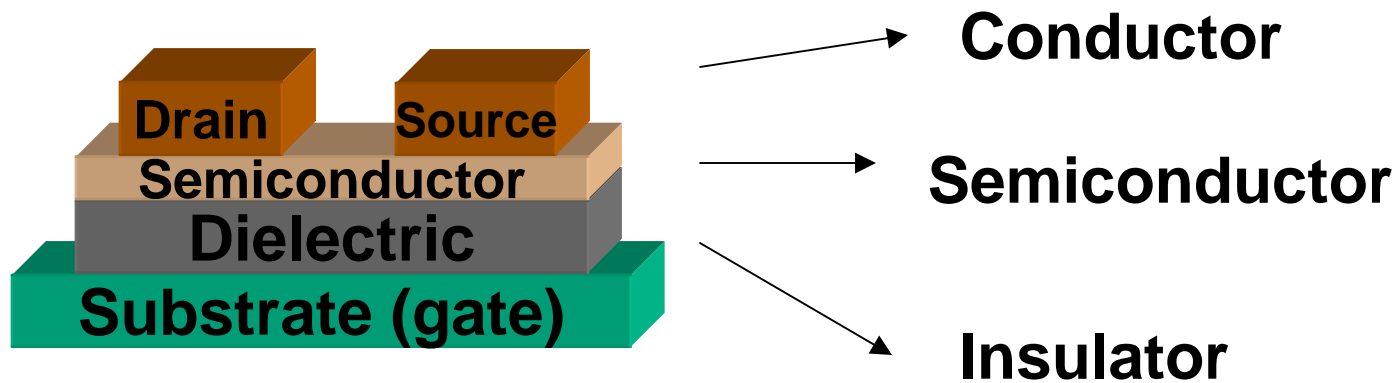


Lucent/E-Ink

Someya et al. PNAS 2004



Materials



Conductors

Vacuum evaporated metal: Au, Ag, Pd

**Solution deposited conducting polymers:
polythiophene (PEDOT), polyaniline**

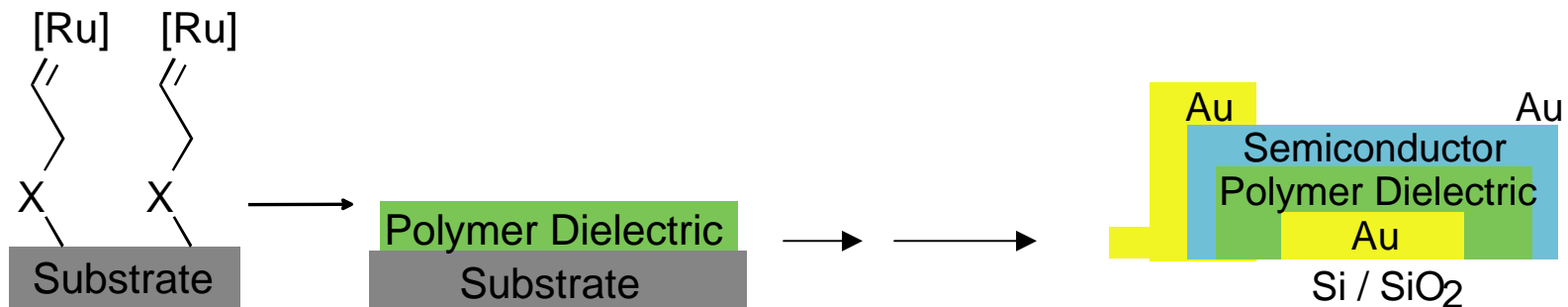
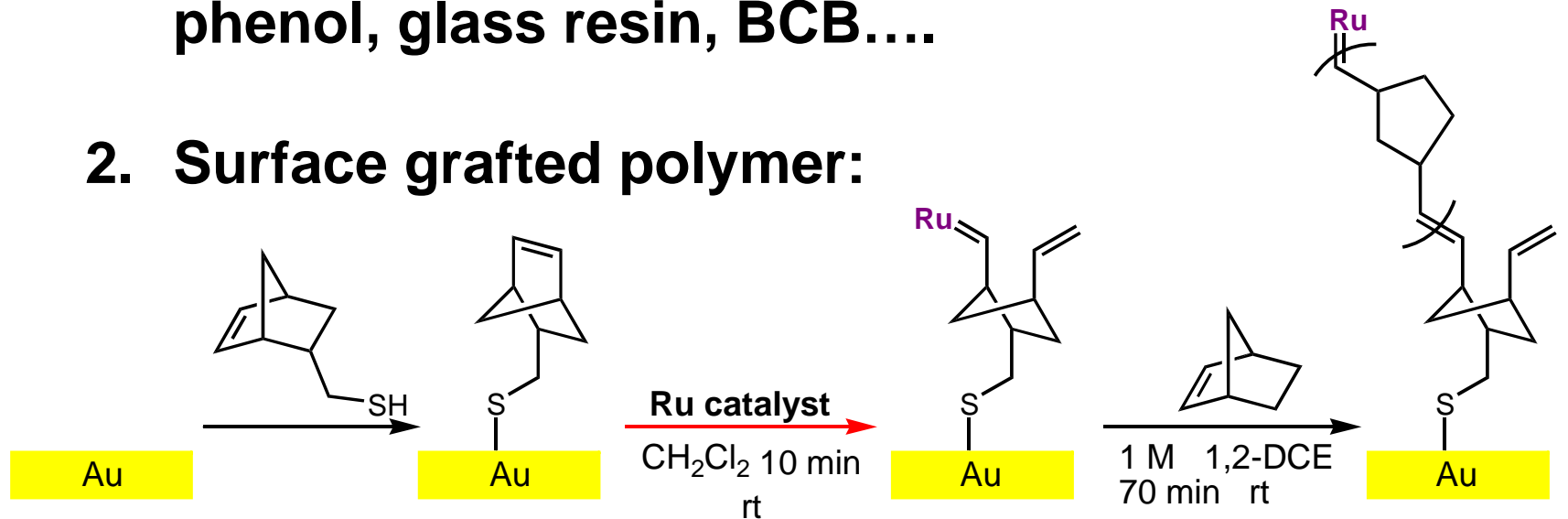
**Solution deposited Au or Ag nanoparticles:
curing temperature 120-200 °C**



Dielectric Materials

1. Spin coated polymer: PMMA, polystyrene, polyvinyl phenol, glass resin, BCB....

2. Surface grafted polymer:

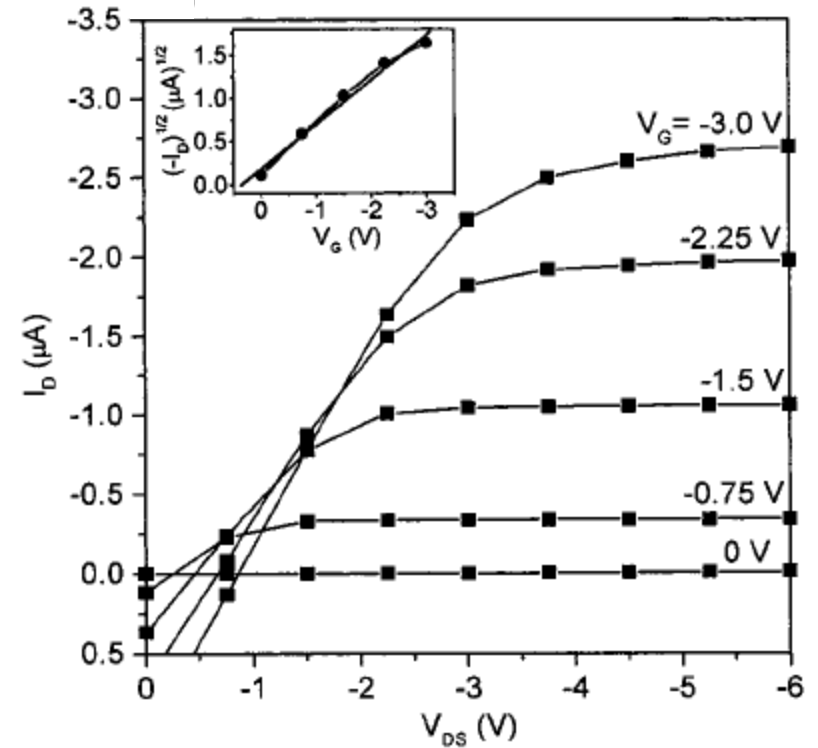
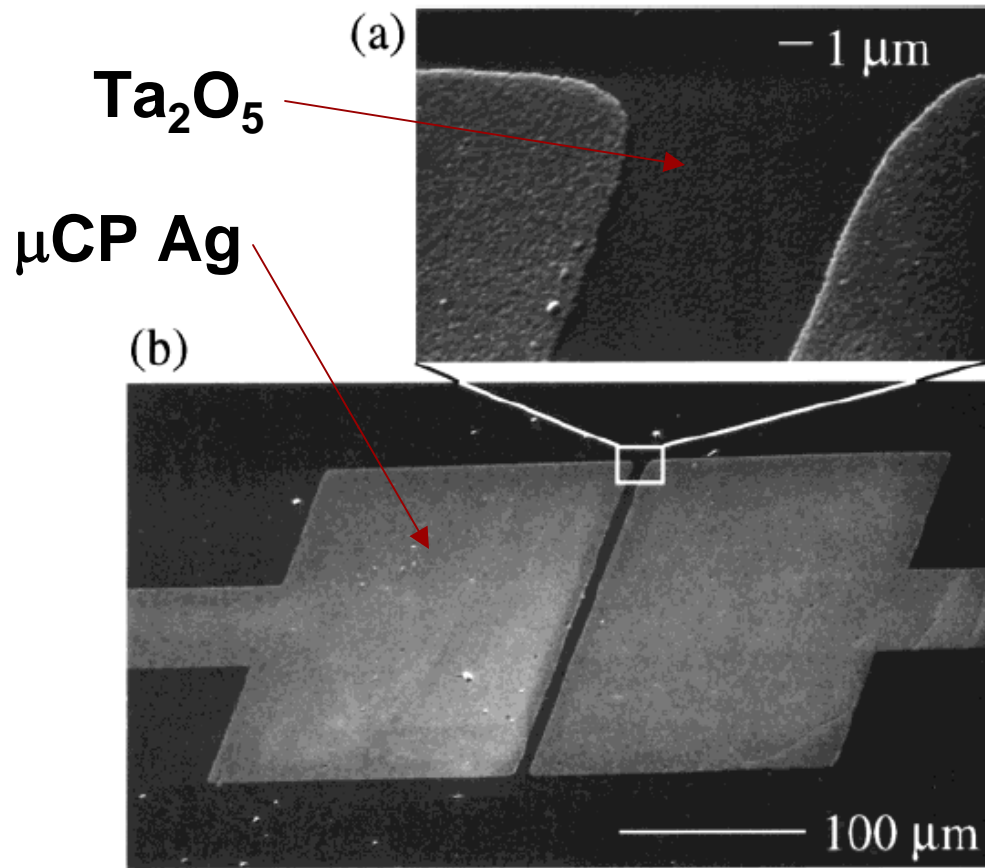


1) I. Rutenburg, O. Scherman, Z. Bao, R. Grubbs, *J. Am. Chem. Soc.*, **126**, 4062-4063, 2004.



Dielectric Materials, con'd

3. Anodized Ta_2O_5 and Hf_2O_5

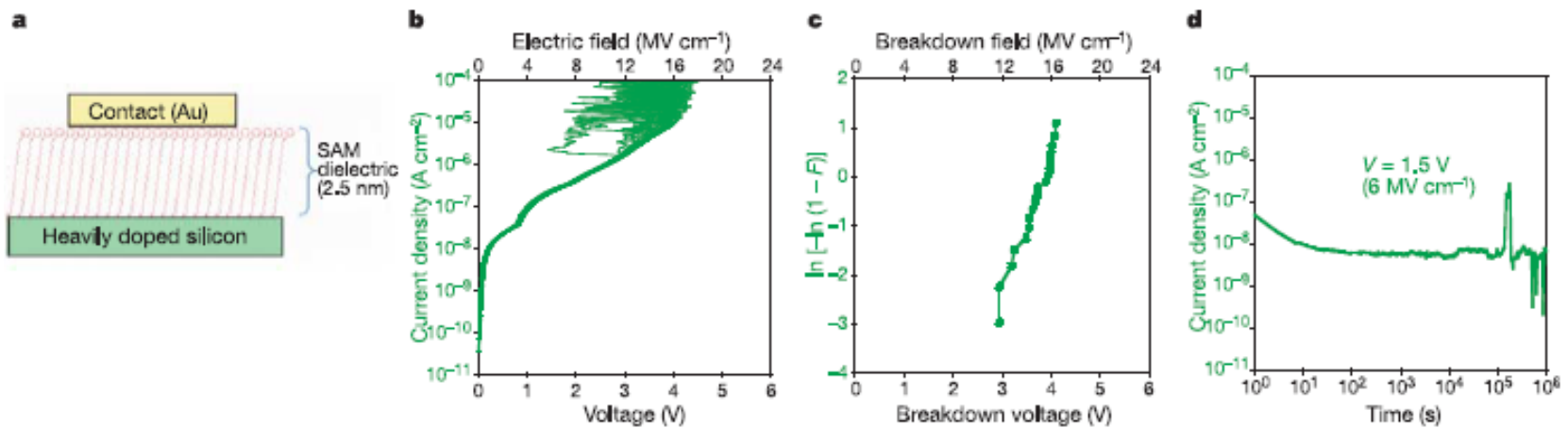
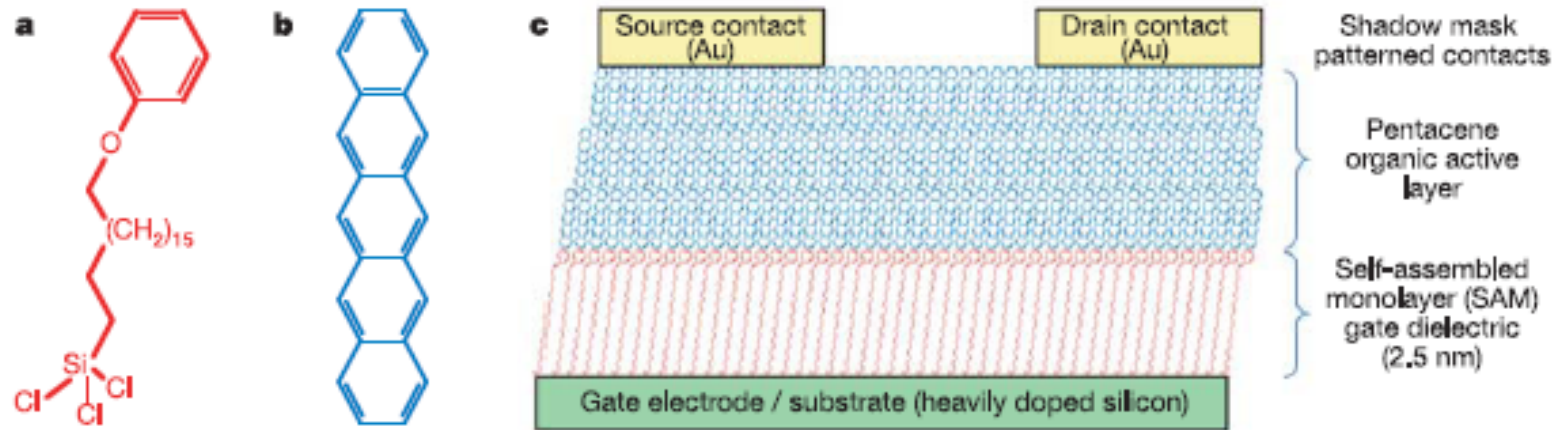


J. Tate, J.A. Rogers, C.D. W. Jones, B. Vyas, D.W. Murphy, W. Li, Z. Bao, R.E. Slusher, A. Dodabalapur, H.E. Katz, *Langmuir* **2000**, *16*, 6054-6060



Dielectric Materials, con'd

4. Self-assembled monolayer



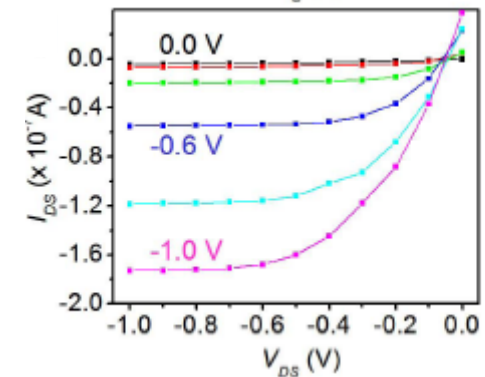
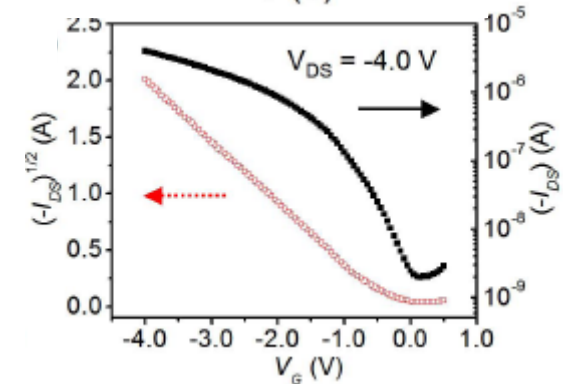
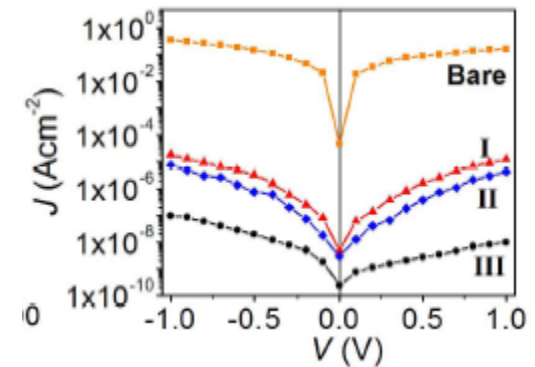
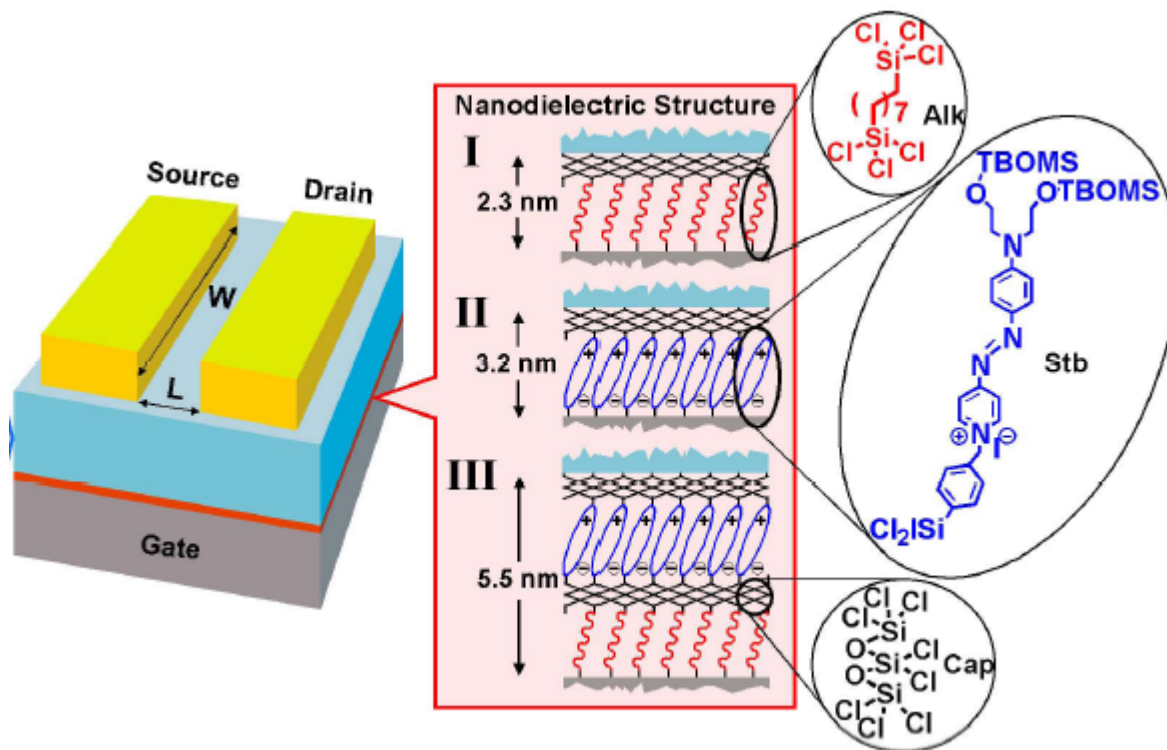
M. Halik et al., Nature, 2005



Dielectric Materials, con'd

4. Self-assembled monolayer

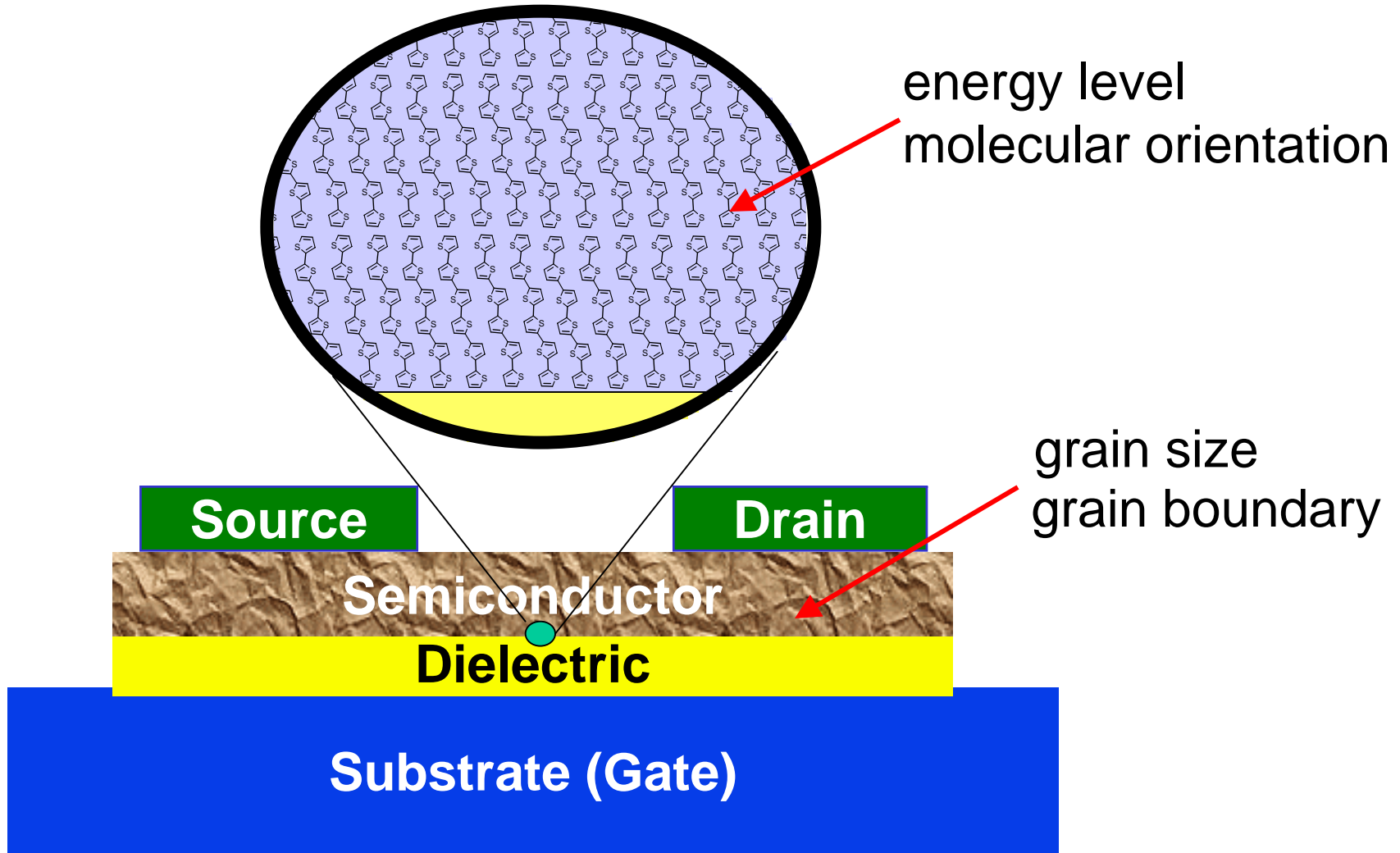
$k = 16$



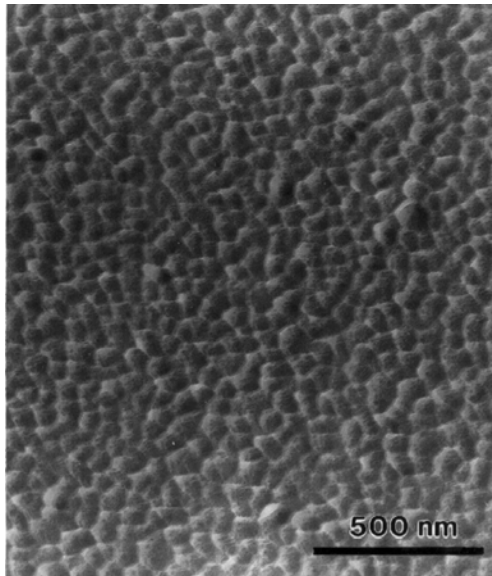
M.H. Yoon, A. Facchetti, T.J. Marks, *PNAS*, 2005



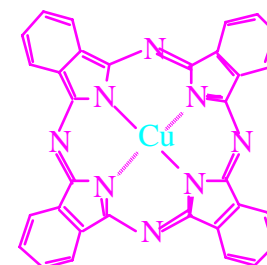
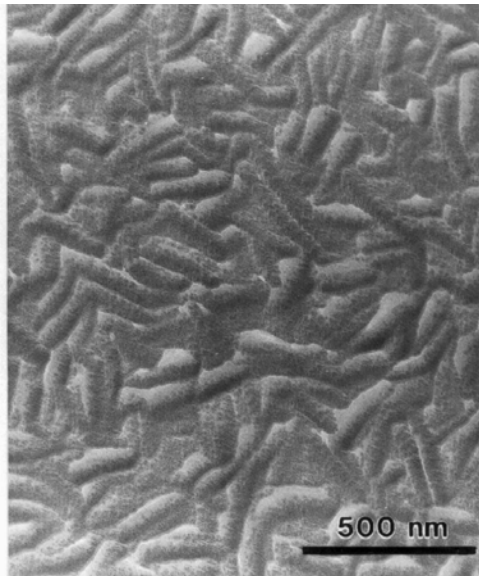
Semiconductor



Substrate temperature = 25 °C

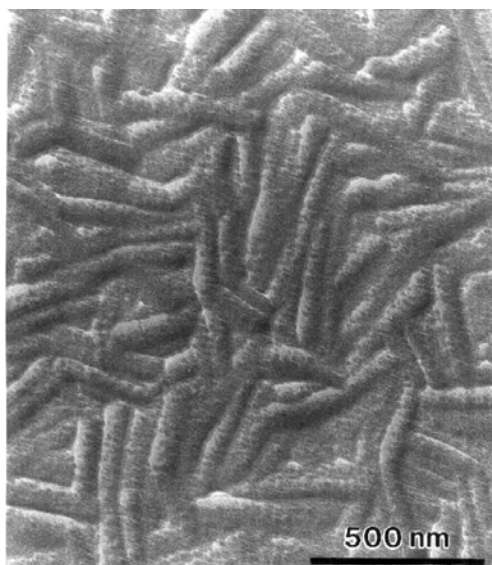


Substrate temperature = 100 °C

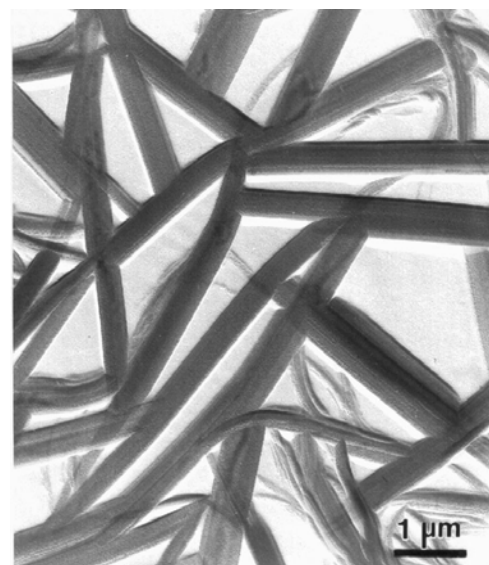


Cu-Pc

Substrate temperature = 125 °C

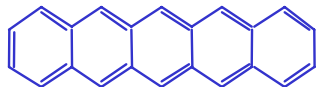


Substrate temperature = 225 °C



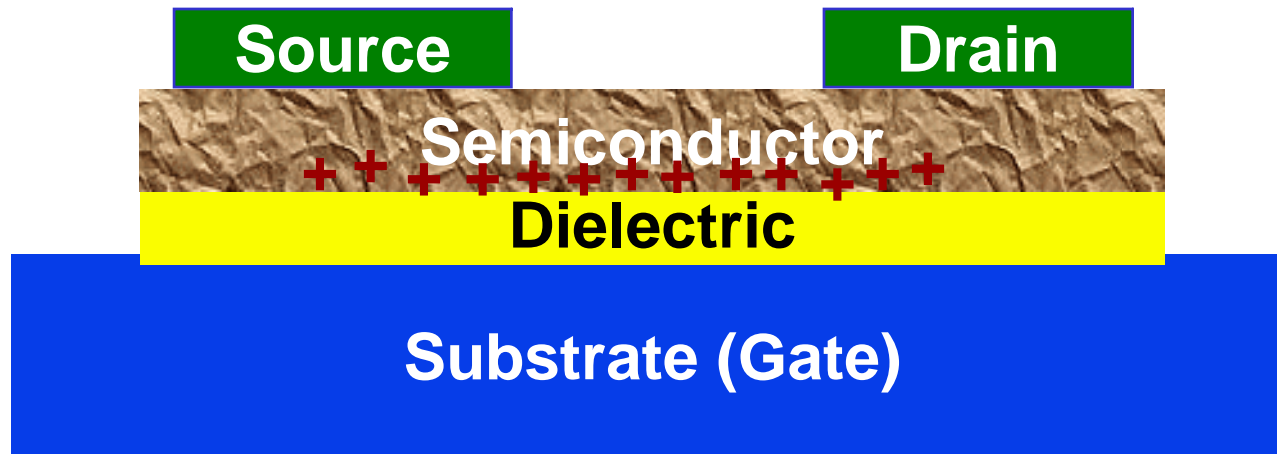
Z. Bao, A.J. Lovinger, A. Dodabalapur, **Adv. Mater.** 9, 42, 1997.

Room temperature mobility of Inorganic semiconductors

Semiconductor	μ_{hole} (cm ² /Vs)	μ_{electron} (cm ² /Vs)
Single crystal Si	480	1500
Hydrogenated α -Si	<0.1	0.1-1
 Pentacene	7 (thin film) 35 (single crystal)	
Rubrene	15 (single crystal)	
Regioregular poly(3-hexyl-thiophene)	0.1	

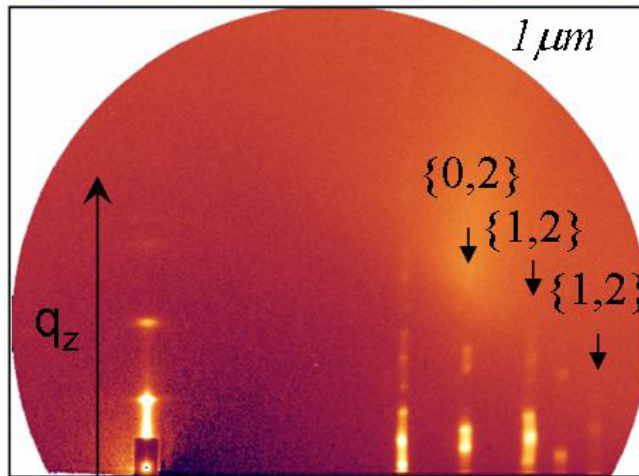
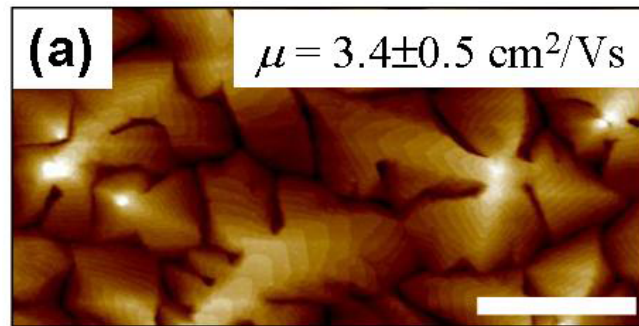


**Charge carriers are induced
mostly in the first 5nm of organic
semiconductor film**

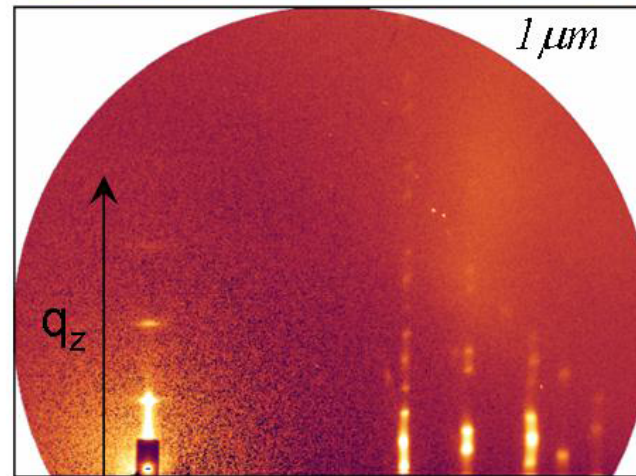
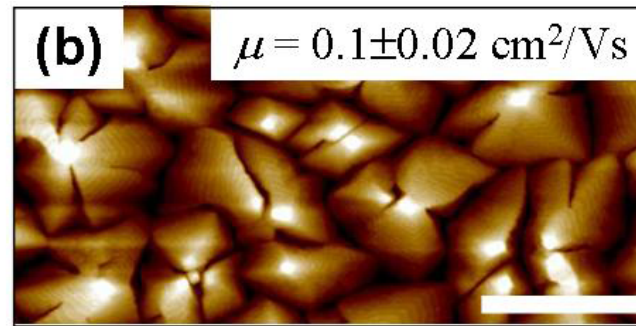


AFM and 2D-GIXD of pentacene (60nm) films on different surfaces

Dr. Mike Ling, Dr. Hoichang Yang, Dr. Tae Joo Shin (BNL)



**Pentacene on HMDS
treated SiO₂**



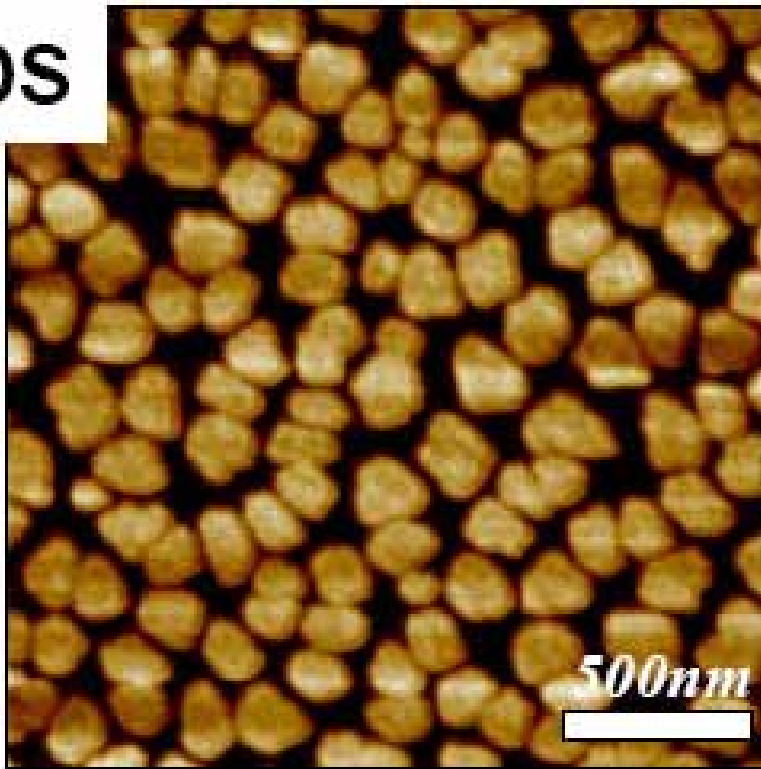
**Pentacene on OTS
treated SiO₂**



AFM Images of Sub-monolayer Pentacene

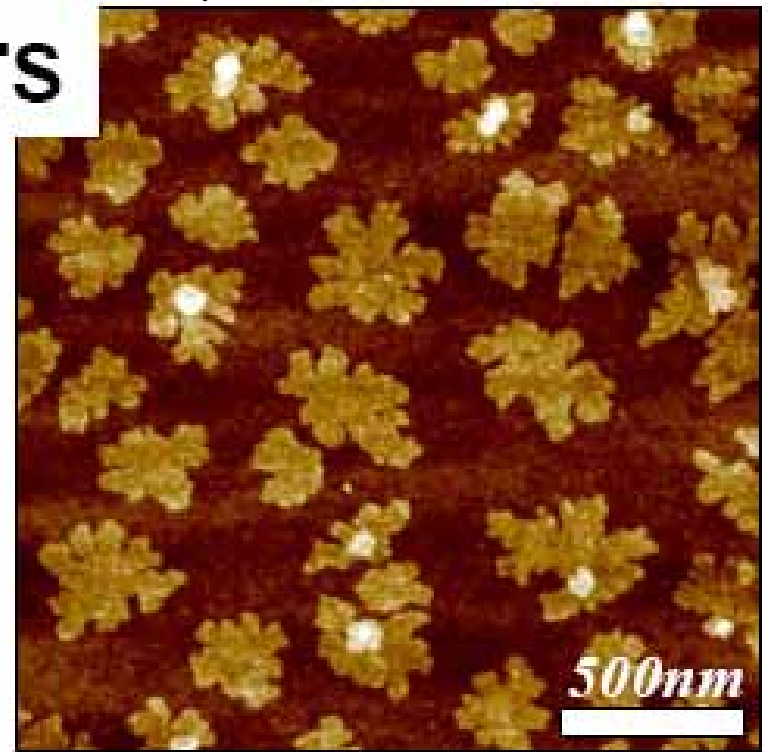
$\mu = 3.4 \text{ cm}^2/\text{Vs}$

HMDS

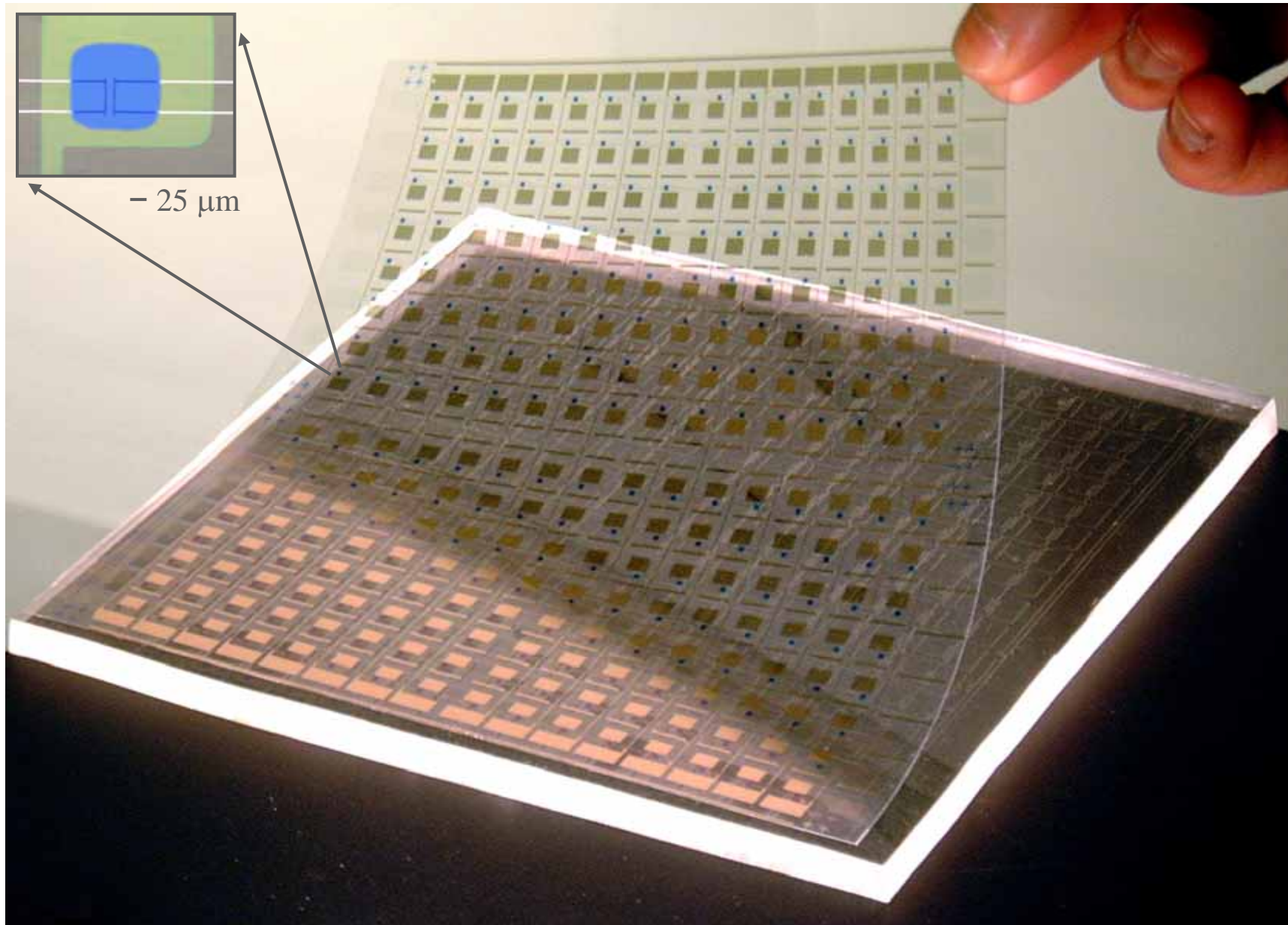


$\mu = 0.1 \text{ cm}^2/\text{Vs}$

OTS



Rubber Stamped Plastic Circuitry for Electronic Paper



PNAS, 2001



Screen printing

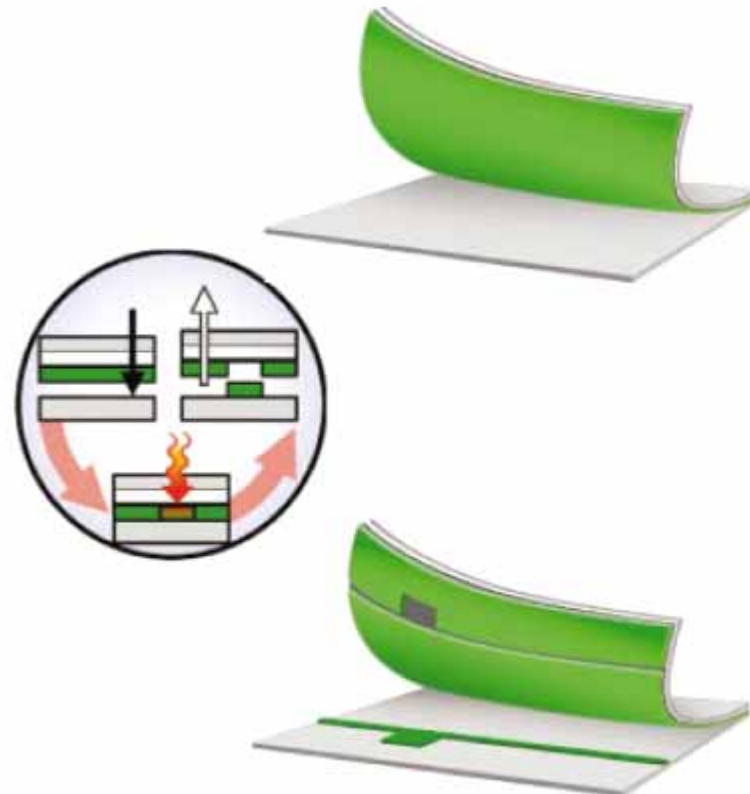


***First all-printed plastic circuit
Lucent Technologies***

Z. Bao et al. *Chem. Mater.* 9, 1299 (1997)
R. Service, *Science*, 278, 383 (1997)

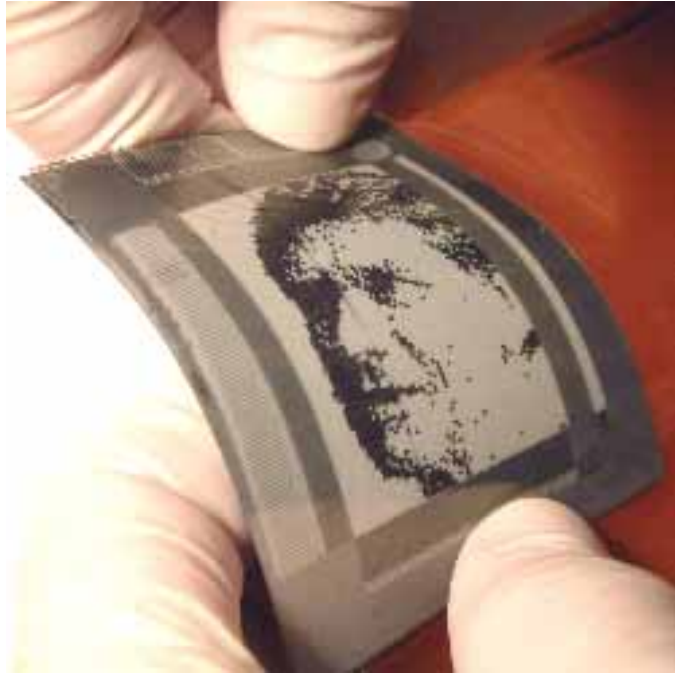


Patterning Technology: Commercial Printer



Blanchet et al., *Appl. Phys. Lett.* 2003, 82, 463-465

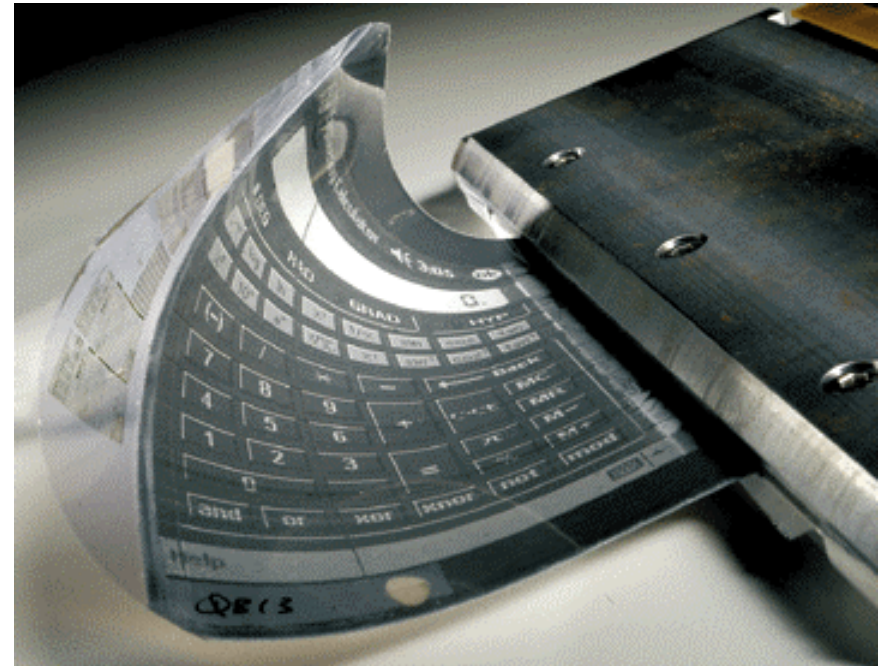
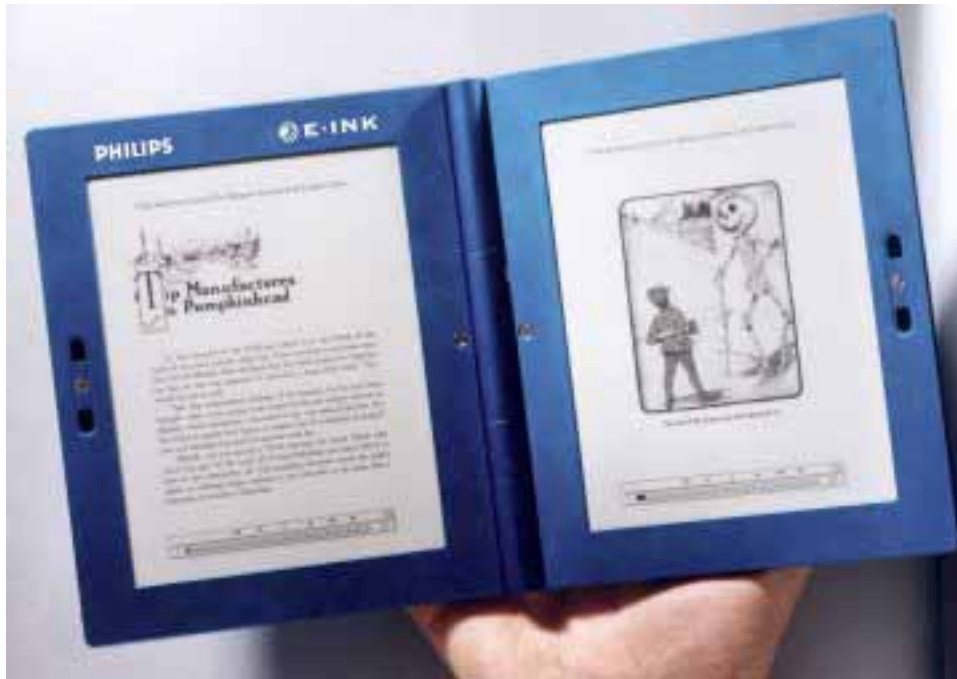
Ink-jet Printing



Plastic Logic



E-book



Philips



Summary

Organic materials have great potential for flexible electronics

Suitable applications need to be identified

More investigation of stability and reliability issues is needed

Better fundamental understanding of charge transport mechanism and morphology control is important – further improvement in mobility



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Dr. Wei You
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Hyunsik Moon
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Dr. Hoichang Yang (RPI)
Dr. Christian Kloc (Bell Labs)
Dr. Andrew Lovinger (Bell Labs)

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